

MECHANICAL CASE OUTLINE

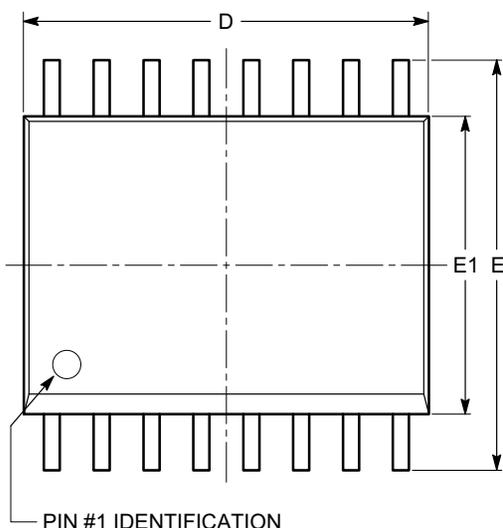
PACKAGE DIMENSIONS

ON Semiconductor®



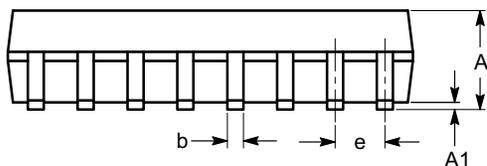
SOIC-16, 300 mils
CASE 751BH-01
ISSUE A

DATE 18 MAR 2009

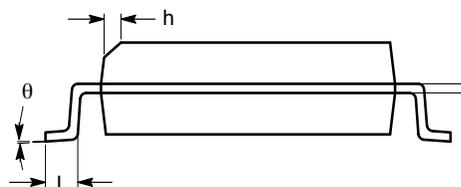


TOP VIEW

SYMBOL	MIN	NOM	MAX
A	2.36	2.49	2.64
A1	0.10		0.30
b	0.33	0.41	0.51
c	0.18	0.23	0.28
D	10.08	10.31	10.49
E	10.01	10.31	10.64
E1	7.39	7.49	7.59
e	1.27 BSC		
h	0.25		0.75
L	0.38	0.81	1.27
θ	0°		8°



SIDE VIEW



END VIEW

Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MS-013.

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DESCRIPTION:	SOIC-16, 300 MILS	PAGE 1 OF 2

